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Details

Product Status	Last Time Buy
Core Processor	XC800
Core Size	8-Bit
Speed	24MHz
Connectivity	CANbus, LINbus, SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	48
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1.75K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	PG-TQFP-64
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xc888clm8ffa5vackxuma1

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Summary of Features
Table 2 Device Profile (cont'd)

Sales Type	Device Type	Program Memory (Kbytes)	Power Supply (V)	Temperature (°C)	Quality Profile
SAK-XC886*/888*-8FFA 3V3	Flash	32	3.3	-40 to 125	Automotive
SAK-XC886*/888*-6FFA 3V3	Flash	24	3.3	-40 to 125	Automotive
SAF-XC886*/888*-8FFA 3V3	Flash	32	3.3	-40 to 85	Automotive
SAF-XC886*/888*-6FFA 3V3	Flash	24	3.3	-40 to 85	Automotive
SAF-XC886*/888*-8FFI 3V3	Flash	32	3.3	-40 to 85	Industrial
SAF-XC886*/888*-6FFI 3V3	Flash	24	3.3	-40 to 85	Industrial

Note: The asterisk () above denotes the device configuration letters from [Table 1](#). Corresponding ROM derivatives will be available on request.*

Note: For variants with LIN BSL support, only LIN BSL is available regardless of the availability of the CAN module.

As this document refers to all the derivatives, some description may not apply to a specific product. For simplicity, all versions are referred to by the term XC886/888 throughout this document.

Ordering Information

The ordering code for Infineon Technologies microcontrollers provides an exact reference to the required product. This ordering code identifies:

- The derivative itself, i.e. its function set, the temperature range, and the supply voltage
- The package and the type of delivery

For the available ordering codes for the XC886/888, please refer to your responsible sales representative or your local distributor.

Note: The ordering codes for the Mask-ROM versions are defined for each product after verification of the respective ROM code.

2.2 Logic Symbol

The logic symbols of the XC886/888 are shown in **Figure 3**.

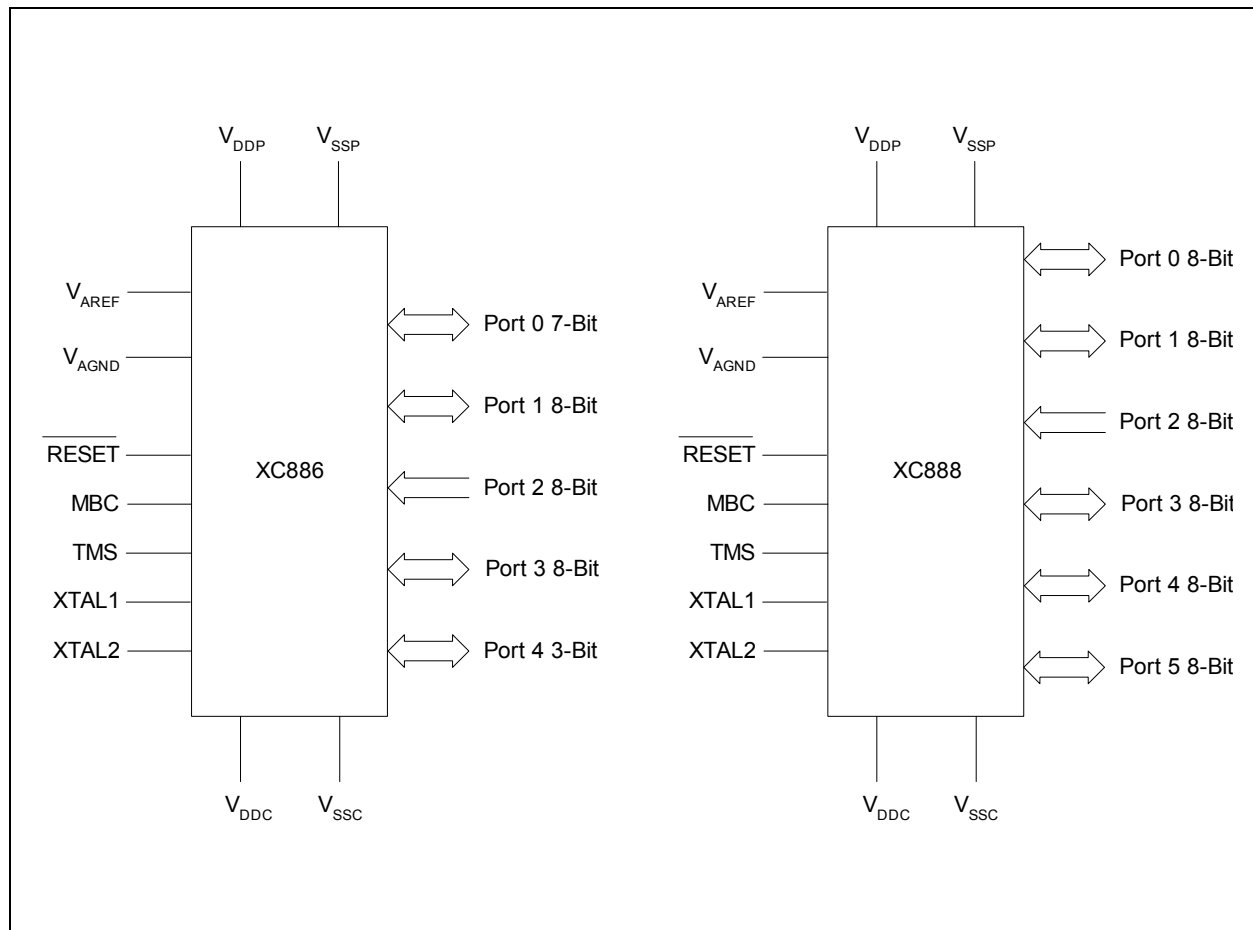


Figure 3 XC886/888 Logic Symbol

General Device Information

2.3 Pin Configuration

The pin configuration of the XC886, which is based on the PG-TQFP-48 package, is shown in [Figure 4](#), while that of the XC888, which is based on the PG-TQFP-64 package, is shown in [Figure 5](#).

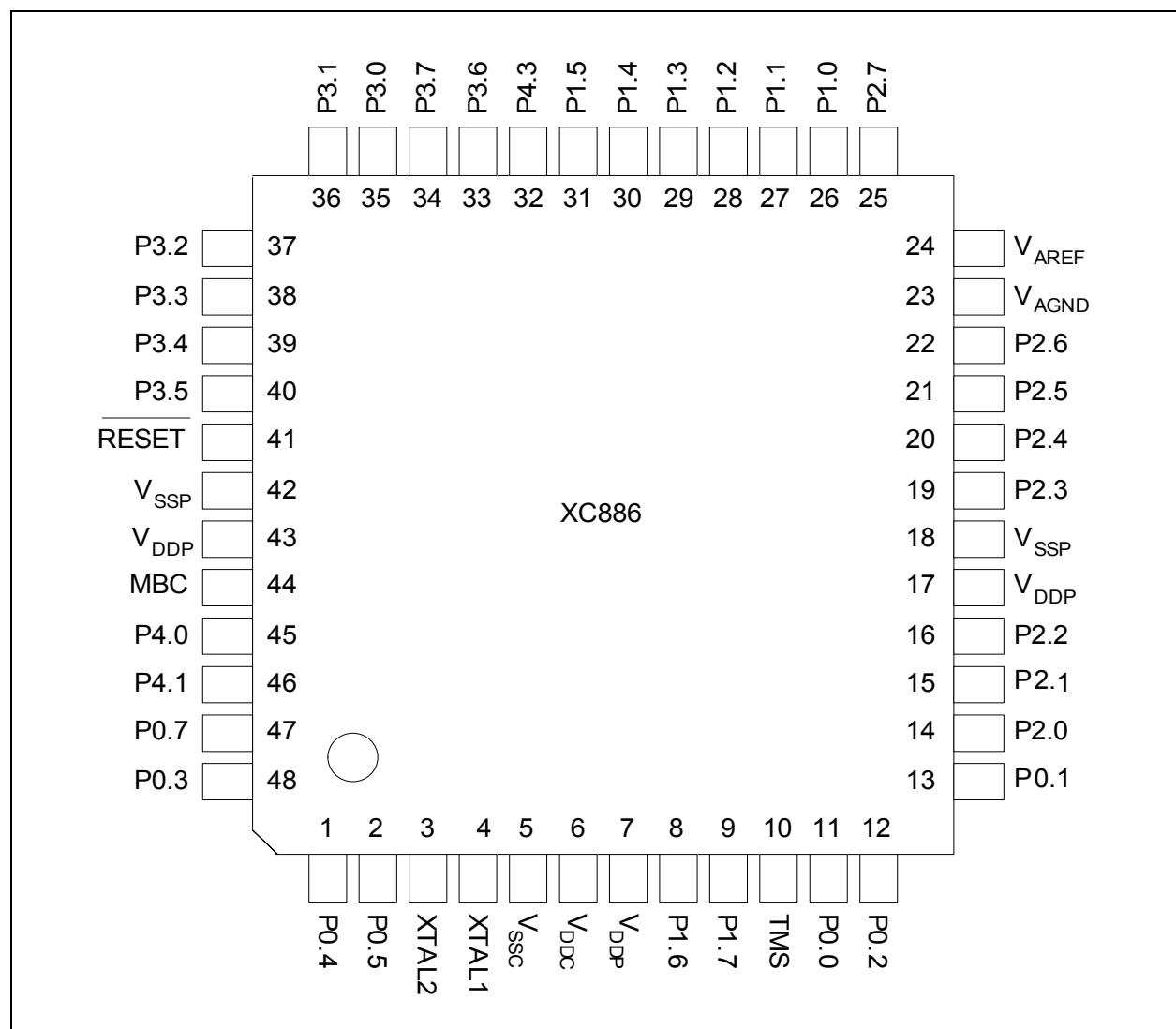


Figure 4 XC886 Pin Configuration, PG-TQFP-48 Package (top view)

General Device Information

Table 3 Pin Definitions and Functions (cont'd)

Symbol	Pin Number (TQFP-48/64)	Type	Reset State	Function
P2		I		Port 2 Port 2 is an 8-bit general purpose input-only port. It can be used as alternate functions for the digital inputs of the JTAG and CCU6. It is also used as the analog inputs for the ADC.
P2.0	14/22		Hi-Z	CCPOS0_0 CCU6 Hall Input 0 EXINT1_0 External Interrupt Input 1 T12HR_2 CCU6 Timer 12 Hardware Run Input TCK_1 JTAG Clock Input CC61_3 Input of Capture/Compare channel 1 AN0 Analog Input 0
P2.1	15/23		Hi-Z	CCPOS1_0 CCU6 Hall Input 1 EXINT2_0 External Interrupt Input 2 T13HR_2 CCU6 Timer 13 Hardware Run Input TDI_1 JTAG Serial Data Input CC62_3 Input of Capture/Compare channel 2 AN1 Analog Input 1
P2.2	16/24		Hi-Z	CCPOS2_0 CCU6 Hall Input 2 CTRAP_1 CCU6 Trap Input CC60_3 Input of Capture/Compare channel 0 AN2 Analog Input 2
P2.3	19/27		Hi-Z	AN3 Analog Input 3
P2.4	20/28		Hi-Z	AN4 Analog Input 4
P2.5	21/29		Hi-Z	AN5 Analog Input 5
P2.6	22/30		Hi-Z	AN6 Analog Input 6
P2.7	25/33		Hi-Z	AN7 Analog Input 7

Functional Description

code or data. Therefore, even though the ROM device contains either a 24-Kbyte or 32-Kbyte ROM, the maximum size of code that can be placed in the ROM is the given size less four bytes.

3.2.1 Memory Protection Strategy

The XC886/888 memory protection strategy includes:

- Read-out protection: The user is able to protect the contents in the Flash (for Flash devices) and ROM (for ROM devices) memory from being read
 - Flash protection is enabled by programming a valid password (8-bit non-zero value) via BSL mode 6.
 - ROM protection is fixed with the ROM mask and is always enabled.
- Flash program and erase protection: This feature is available only for Flash devices.

3.2.1.1 Flash Memory Protection

As long as a valid password is available, all external access to the device, including the Flash, will be blocked.

For additional security, the Flash hardware protection can be enabled to implement a second layer of read-out protection, as well as to enable program and erase protection.

Flash hardware protection is available only for Flash devices and comes in two modes:

- Mode 0: Only the P-Flash is protected; the D-Flash is unprotected
- Mode 1: Both the P-Flash and D-Flash are protected

The selection of each protection mode and the restrictions imposed are summarized in [Table 4](#).

Table 4 Flash Protection Modes

Flash Protection	Without hardware protection			With hardware protection	
Hardware Protection Mode	-	0	1		
Activation	Program a valid password via BSL mode 6				
Selection	Bit 4 of password = 0	Bit 4 of password = 1	MSB of password = 0	Bit 4 of password = 1	MSB of password = 1
P-Flash contents can be read by	Read instructions in any program memory	Read instructions in the P-Flash		Read instructions in the P-Flash or D-Flash	
External access to P-Flash	Not possible	Not possible		Not possible	

Functional Description

The page register has the following definition:

MOD_PAGE

Page Register for module MOD

Reset Value: 00_H

7	6	5	4	3	2	1	0
OP		STNR		0	PAGE		
w		w		r	rw		

Field	Bits	Type	Description
PAGE	[2:0]	rw	Page Bits When written, the value indicates the new page. When read, the value indicates the currently active page.
STNR	[5:4]	w	Storage Number This number indicates which storage bit field is the target of the operation defined by bit field OP. If OP = 10 _B , the contents of PAGE are saved in STx before being overwritten with the new value. If OP = 11 _B , the contents of PAGE are overwritten by the contents of STx. The value written to the bit positions of PAGE is ignored. 00 ST0 is selected. 01 ST1 is selected. 10 ST2 is selected. 11 ST3 is selected.

Functional Description

Field	Bits	Type	Description
OP	[7:6]	w	Operation 0X Manual page mode. The value of STNR is ignored and PAGE is directly written. 10 New page programming with automatic page saving. The value written to the bit positions of PAGE is stored. In parallel, the previous contents of PAGE are saved in the storage bit field STx indicated by STNR. 11 Automatic restore page action. The value written to the bit positions PAGE is ignored and instead, PAGE is overwritten by the contents of the storage bit field STx indicated by STNR.
0	3	r	Reserved Returns 0 if read; should be written with 0.

3.2.3 Bit Protection Scheme

The bit protection scheme prevents direct software writing of selected bits (i.e., protected bits) using the PASSWD register. When the bit field MODE is 11_B, writing 10011_B to the bit field PASS opens access to writing of all protected bits, and writing 10101_B to the bit field PASS closes access to writing of all protected bits. In both cases, the value of the bit field MODE is not changed even if PASSWD register is written with 98_H or A8_H. It can only be changed when bit field PASS is written with 11000_B, for example, writing D0_H to PASSWD register disables the bit protection scheme.

Note that access is opened for maximum 32 CCLKs if the “close access” password is not written. If “open access” password is written again before the end of 32 CCLK cycles, there will be a recount of 32 CCLK cycles. The protected bits include the N- and K-Divider bits, NDIV and KDIV; the Watchdog Timer enable bit, WDTEN; and the power-down and slow-down enable bits, PD and SD.

Functional Description
Table 8 SCU Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
BC _H	NMISR Reset: 00_H NMI Status Register	Bit Field	0	FNMI ECC	FNMI VDDP	FNMI VDD	FNMI OCDS	FNMI FLASH	FNMI PLL	FNMI WDT
		Type	r	rwh	rwh	rwh	rwh	rwh	rwh	rwh
BD _H	BCON Reset: 00_H Baud Rate Control Register	Bit Field	BGSEL		0	BRDIS	BRPRE			R
		Type	rw		r	rw	rw			rw
BE _H	BG Reset: 00_H Baud Rate Timer/Reload Register	Bit Field	BR_VALUE							
		Type	rwh							
E9 _H	FDCON Reset: 00_H Fractional Divider Control Register	Bit Field	BGS	SYNE N	ERRS YN	EOFS YN	BRK	NDOV	FDM	FDEN
		Type	rw	rw	rwh	rwh	rwh	rwh	rw	rw
EA _H	FDSTEP Reset: 00_H Fractional Divider Reload Register	Bit Field	STEP							
		Type	rw							
EB _H	FDRES Reset: 00_H Fractional Divider Result Register	Bit Field	RESULT							
		Type	rh							
RMAP = 0, PAGE 1										
B3 _H	ID Reset: UU_H Identity Register	Bit Field	PRODID					VERID		
		Type	r					r		
B4 _H	PMCON0 Reset: 00_H Power Mode Control Register 0	Bit Field	0	WDT RST	WKRS	WK SEL	SD	PD	WS	
		Type	r	rwh	rwh	rw	rw	rwh	rw	
B5 _H	PMCON1 Reset: 00_H Power Mode Control Register 1	Bit Field	0	CDC_ DIS	CAN_ DIS	MDU_ DIS	T2_ DIS	CCU_ DIS	SSC_ DIS	ADC_ DIS
		Type	r	rw	rw	rw	rw	rw	rw	rw
B6 _H	OSC_CON Reset: 08_H OSC Control Register	Bit Field	0			OSC PD	XPD	OSC SS	ORD RES	OSCR
		Type	r			rw	rw	rw	rwh	rh
B7 _H	PLL_CON Reset: 90_H PLL Control Register	Bit Field	NDIV				VCO BYP	OSC DISC	RESL D	LOCK
		Type	rw				rw	rw	rwh	rh
BA _H	CMCON Reset: 10_H Clock Control Register	Bit Field	VCO SEL	KDIV	0	FCCF G	CLKREL			
		Type	rw	rw	r	rw	rw			
BB _H	PASSWD Reset: 07_H Password Register	Bit Field	PASS					PROT ECT_S	MODE	
		Type	wh					rh	rw	
BC _H	FEAL Reset: 00_H Flash Error Address Register Low	Bit Field	ECCERRADDR							
		Type	rh							
BD _H	FEAH Reset: 00_H Flash Error Address Register High	Bit Field	ECCERRADDR							
		Type	rh							

Functional Description
Table 14 CCU6 Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
FE _H	CCU6_CMPSTATL Reset: 00_H Compare State Register Low	Bit Field	0	CC63 ST	CC POS2	CC POS1	CC POS0	CC62 ST	CC61 ST	CC60 ST
		Type	r	rh	rh	rh	rh	rh	rh	rh
FF _H	CCU6_CMPSTATH Reset: 00_H Compare State Register High	Bit Field	T13IM	COUT 63PS	COUT 62PS	CC62 PS	COUT 61PS	CC61 PS	COUT 60PS	CC60 PS
		Type	rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh

3.2.4.11 UART1 Registers

The UART1 SFRs can be accessed in the mapped memory area (RMAP = 1).

Table 15 UART1 Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 1										
C8 _H	SCON Reset: 00_H Serial Channel Control Register	Bit Field	SM0	SM1	SM2	REN	TB8	RB8	TI	RI
		Type	rw	rw	rw	rw	rw	rwh	rwh	rwh
C9 _H	SBUF Reset: 00_H Serial Data Buffer Register	Bit Field	VAL							
		Type	rwh							
CA _H	BCON Reset: 00_H Baud Rate Control Register	Bit Field	0				BRPRE			R
		Type	r				rw			rw
CB _H	BG Reset: 00_H Baud Rate Timer/Reload Register	Bit Field	BR_VALUE							
		Type	rwh							
CC _H	FDCON Reset: 00_H Fractional Divider Control Register	Bit Field	0					NDOV	FDM	FDEN
		Type	r					rwh	rw	rw
CD _H	FDSTEP Reset: 00_H Fractional Divider Reload Register	Bit Field	STEP							
		Type	rw							
CE _H	FDRES Reset: 00_H Fractional Divider Result Register	Bit Field	RESULT							
		Type	rh							

3.3 Flash Memory

The Flash memory provides an embedded user-programmable non-volatile memory, allowing fast and reliable storage of user code and data. It is operated from a single 2.5 V supply from the Embedded Voltage Regulator (EVR) and does not require additional programming or erasing voltage. The sectorization of the Flash memory allows each sector to be erased independently.

Features

- In-System Programming (ISP) via UART
- In-Application Programming (IAP)
- Error Correction Code (ECC) for dynamic correction of single-bit errors
- Background program and erase operations for CPU load minimization
- Support for aborting erase operation
- Minimum program width¹⁾ of 32-byte for D-Flash and 64-byte for P-Flash
- 1-sector minimum erase width
- 1-byte read access
- Flash is delivered in erased state (read all zeros)
- Operating supply voltage: 2.5 V \pm 7.5 %
- Read access time: $3 \times t_{\text{CCLK}} = 125 \text{ ns}^{2)}$
- Program time: $248256 / f_{\text{SYS}} = 2.6 \text{ ms}^{3)}$
- Erase time: $9807360 / f_{\text{SYS}} = 102 \text{ ms}^{3)}$

1) P-Flash: 64-byte wordline can only be programmed once, i.e., one gate disturb allowed.
D-Flash: 32-byte wordline can be programmed twice, i.e., two gate disturbs allowed.

2) Values shown here are typical values. $f_{\text{sys}} = 96 \text{ MHz} \pm 7.5\%$ ($f_{\text{CCLK}} = 24 \text{ MHz} \pm 7.5\%$) is the maximum frequency range for Flash read access.

3) Values shown here are typical values. $f_{\text{sys}} = 96 \text{ MHz} \pm 7.5\%$ is the only frequency range for Flash programming and erasing. f_{sysmin} is used for obtaining the worst case timing.

Functional Description

3.4 Interrupt System

The XC800 Core supports one non-maskable interrupt (NMI) and 14 maskable interrupt requests. In addition to the standard interrupt functions supported by the core, e.g., configurable interrupt priority and interrupt masking, the XC886/888 interrupt system provides extended interrupt support capabilities such as the mapping of each interrupt vector to several interrupt sources to increase the number of interrupt sources supported, and additional status registers for detecting and determining the interrupt source.

3.4.1 Interrupt Source

Figure 13 to **Figure 17** give a general overview of the interrupt sources and nodes, and their corresponding control and status flags.

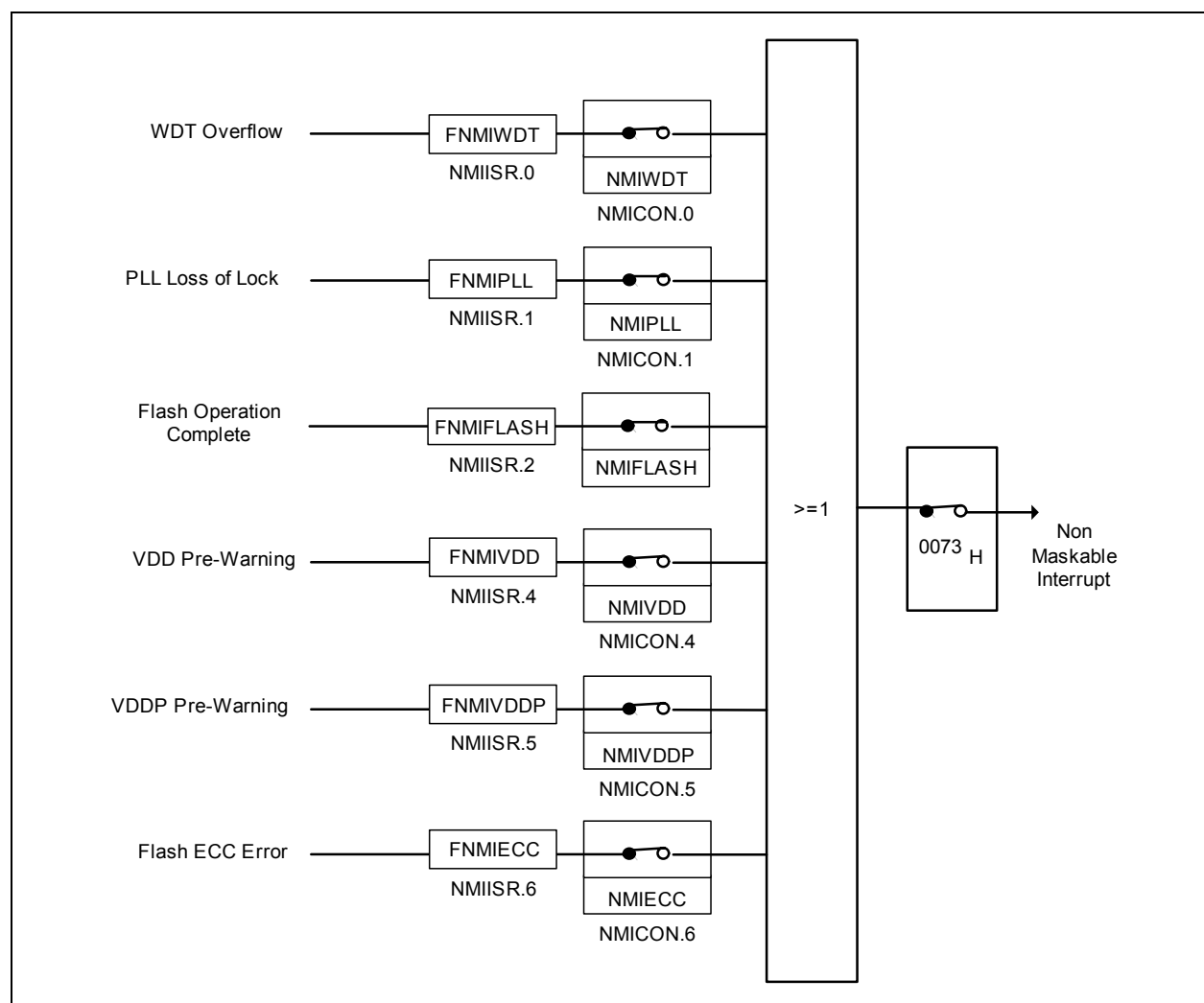


Figure 13 Non-Maskable Interrupt Request Sources

Functional Description

3.4.2 Interrupt Source and Vector

Each interrupt event source has an associated interrupt vector address for the interrupt node it belongs to. This vector is accessed to service the corresponding interrupt node request. The interrupt service of each interrupt source can be individually enabled or disabled via an enable bit. The assignment of the XC886/888 interrupt sources to the interrupt vector address and the corresponding interrupt node enable bits are summarized in [Table 20](#).

Table 20 Interrupt Vector Addresses

Interrupt Source	Vector Address	Assignment for XC886/888	Enable Bit	SFR
NMI	0073 _H	Watchdog Timer NMI	NMIWDT	NMICON
		PLL NMI	NMIPLL	
		Flash NMI	NMIFLASH	
		VDDC Prewarning NMI	NMIVDD	
		VDDP Prewarning NMI	NMIVDDP	
		Flash ECC NMI	NMIECC	
XINTR0	0003 _H	External Interrupt 0	EX0	IEN0
XINTR1	000B _H	Timer 0	ET0	
XINTR2	0013 _H	External Interrupt 1	EX1	
XINTR3	001B _H	Timer 1	ET1	
XINTR4	0023 _H	UART	ES	
XINTR5	002B _H	T2	ET2	
		UART Fractional Divider (Normal Divider Overflow)		
		MultiCAN Node 0		
		LIN		

3.5 Parallel Ports

The XC886 has 34 port pins organized into five parallel ports, Port 0 (P0) to Port 4 (P4), while the XC888 has 48 port pins organized into six parallel ports, Port 0 (P0) to Port 5 (P5). Each pin has a pair of internal pull-up and pull-down devices that can be individually enabled or disabled. Ports P0, P1, P3, P4 and P5 are bidirectional and can be used as general purpose input/output (GPIO) or to perform alternate input/output functions for the on-chip peripherals. When configured as an output, the open drain mode can be selected. Port P2 is an input-only port, providing general purpose input functions, alternate input functions for the on-chip peripherals, and also analog inputs for the Analog-to-Digital Converter (ADC).

Bidirectional Port Features

- Configurable pin direction
- Configurable pull-up/pull-down devices
- Configurable open drain mode
- Transfer of data through digital inputs and outputs (general purpose I/O)
- Alternate input/output for on-chip peripherals

Input Port Features

- Configurable input driver
- Configurable pull-up/pull-down devices
- Receive of data through digital input (general purpose input)
- Alternate input for on-chip peripherals
- Analog input for ADC module

Functional Description

Table 25 shows the VCO range for the XC886/888.

Table 25 VCO Range

f_{VCOmin}	f_{VCOmax}	$f_{VCOFREEmin}$	$f_{VCOFREEmax}$	Unit
150	200	20	80	MHz
100	150	10	80	MHz

3.8.1 Recommended External Oscillator Circuits

The oscillator circuit, a Pierce oscillator, is designed to work with both, an external crystal oscillator or an external stable clock source. It basically consists of an inverting amplifier and a feedback element with XTAL1 as input, and XTAL2 as output.

When using a crystal, a proper external oscillator circuitry must be connected to both pins, XTAL1 and XTAL2. The crystal frequency can be within the range of 4 MHz to 12 MHz. Additionally, it is necessary to have two load capacitances C_{X1} and C_{X2} , and depending on the crystal type, a series resistor R_{X2} , to limit the current. A test resistor R_Q may be temporarily inserted to measure the oscillation allowance (negative resistance) of the oscillator circuitry. R_Q values are typically specified by the crystal vendor. The C_{X1} and C_{X2} values shown in **Figure 25** can be used as starting points for the negative resistance evaluation and for non-productive systems. The exact values and related operating range are dependent on the crystal frequency and have to be determined and optimized together with the crystal vendor using the negative resistance method. Oscillation measurement with the final target system is strongly recommended to verify the input amplitude at XTAL1 and to determine the actual oscillation allowance (margin negative resistance) for the oscillator-crystal system.

When using an external clock signal, the signal must be connected to XTAL1. XTAL2 is left open (unconnected).

The oscillator can also be used in combination with a ceramic resonator. The final circuitry must also be verified by the resonator vendor. **Figure 25** shows the recommended external oscillator circuitries for both operating modes, external crystal mode and external input clock mode.

Functional Description
3.23 Chip Identification Number

The XC886/888 identity (ID) register is located at Page 1 of address B3_H. The value of ID register is 09_H for Flash devices and 22_H for ROM devices. However, for easy identification of product variants, the Chip Identification Number, which is an unique number assigned to each product variant, is available. The differentiation is based on the product, variant type and device step information.

Two methods are provided to read a device's chip identification number:

- In-application subroutine, GET_CHIP_INFO
- Bootstrap loader (BSL) mode A

Table 36 lists the chip identification numbers of available XC886/888 Flash and ROM device variants.

Table 36 Chip Identification Number

Product Variant	Chip Identification Number		
	AA-Step	AB-Step	AC-Step
Flash Devices			
XC886CLM-8FFA 3V3	-	09500102 _H	0B500102 _H
XC888CLM-8FFA 3V3	-	09500103 _H	0B500103 _H
XC886LM-8FFA 3V3	-	09500122 _H	0B500122 _H
XC888LM-8FFA 3V3	-	09500123 _H	0B500123 _H
XC886CLM-6FFA 3V3	-	09551502 _H	0B551502 _H
XC888CLM-6FFA 3V3	-	09551503 _H	0B551503 _H
XC886LM-6FFA 3V3	-	09551522 _H	0B551522 _H
XC888LM-6FFA 3V3	-	09551523 _H	0B551523 _H
XC886CM-8FFA 3V3	-	09580102 _H	0B580102 _H
XC888CM-8FFA 3V3	-	09580103 _H	0B580103 _H
XC886C-8FFA 3V3	-	09580142 _H	0B580142 _H
XC888C-8FFA 3V3	-	09580143 _H	0B580143 _H
XC886-8FFA 3V3	-	09580162 _H	0B580162 _H
XC888-8FFA 3V3	-	09580163 _H	0B580163 _H
XC886CM-6FFA 3V3	-	095D1502 _H	0B5D1502 _H
XC888CM-6FFA 3V3	-	095D1503 _H	0B5D1503 _H
XC886C-6FFA 3V3	-	095D1542 _H	0B5D1542 _H
XC888C-6FFA 3V3	-	095D1543 _H	0B5D1543 _H

Functional Description

Table 36 **Chip Identification Number (cont'd)**

Product Variant	Chip Identification Number		
	AA-Step	AB-Step	AC-Step
XC886LM-6RFA 3V3	22411522 _H	-	-
XC888LM-6RFA 3V3	22411523 _H	-	-
XC886CM-8RFA 3V3	22480502 _H	-	-
XC888CM-8RFA 3V3	22480503 _H	-	-
XC886C-8RFA 3V3	22480542 _H	-	-
XC888C-8RFA 3V3	22480543 _H	-	-
XC886-8RFA 3V3	22480562 _H	-	-
XC888-8RFA 3V3	22480563 _H	-	-
XC886CM-6RFA 3V3	22491502 _H	-	-
XC888CM-6RFA 3V3	22491503 _H	-	-
XC886C-6RFA 3V3	22491542 _H	-	-
XC888C-6RFA 3V3	22491543 _H	-	-
XC886-6RFA 3V3	22491562 _H	-	-
XC888-6RFA 3V3	22491563 _H	-	-
XC886CLM-8RFA 5V	22800502 _H	-	-
XC888CLM-8RFA 5V	22800503 _H	-	-
XC886LM-8RFA 5V	22800522 _H	-	-
XC888LM-8RFA 5V	22800523 _H	-	-
XC886CLM-6RFA 5V	22811502 _H	-	-
XC888CLM-6RFA 5V	22811503 _H	-	-
XC886LM-6RFA 5V	22811522 _H	-	-
XC888LM-6RFA 5V	22811523 _H	-	-
XC886CM-8RFA 5V	22880502 _H	-	-
XC888CM-8RFA 5V	22880503 _H	-	-
XC886C-8RFA 5V	22880542 _H	-	-
XC888C-8RFA 5V	22880543 _H	-	-
XC886-8RFA 5V	22880562 _H	-	-
XC888-8RFA 5V	22880563 _H	-	-
XC886CM-6RFA 5V	22891502 _H	-	-

Electrical Parameters

4.1.3 Operating Conditions

The following operating conditions must not be exceeded in order to ensure correct operation of the XC886/888. All parameters mentioned in the following table refer to these operating conditions, unless otherwise noted.

Table 37 Operating Condition Parameters

Parameter	Symbol	Limit Values		Unit	Notes/ Conditions
		min.	max.		
Digital power supply voltage	V_{DDP}	4.5	5.5	V	5V Device
Digital power supply voltage	V_{DDP}	3.0	3.6	V	3.3V Device
Digital ground voltage	V_{SS}	0		V	
Digital core supply voltage	V_{DDC}	2.3	2.7	V	
System Clock Frequency ¹⁾	f_{SYS}	88.8	103.2	MHz	
Ambient temperature	T_A	-40	85	°C	SAF- XC886/888...
		-40	125	°C	SAK- XC886/888...

1) f_{SYS} is the PLL output clock. During normal operating mode, CPU clock is $f_{SYS} / 4$. Please refer to [Figure 26](#) for detailed description.

Electrical Parameters
Table 38 Input/Output Characteristics (Operating Conditions apply) (cont'd)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			min.	max.		
Maximum current out of V_{SS}	I_{MVSS}	SR	–	120	mA	³⁾
$V_{DDP} = 3.3 \text{ V Range}$						
Output low voltage	V_{OL}	CC	–	1.0	V	$I_{OL} = 8 \text{ mA}$
			–	0.4	V	$I_{OL} = 2.5 \text{ mA}$
Output high voltage	V_{OH}	CC	$V_{DDP} - 1.0$	–	V	$I_{OH} = -8 \text{ mA}$
			$V_{DDP} - 0.4$	–	V	$I_{OH} = -2.5 \text{ mA}$
Input low voltage on port pins (all except P0.0 & P0.1)	V_{ILP}	SR	–	$0.3 \times V_{DDP}$	V	CMOS Mode
Input low voltage on P0.0 & P0.1	V_{ILP0}	SR	-0.2	$0.3 \times V_{DDP}$	V	CMOS Mode
Input low voltage on RESET pin	V_{ILR}	SR	–	$0.3 \times V_{DDP}$	V	CMOS Mode
Input low voltage on TMS pin	V_{ILT}	SR	–	$0.3 \times V_{DDP}$	V	CMOS Mode
Input high voltage on port pins (all except P0.0 & P0.1)	V_{IHP}	SR	$0.7 \times V_{DDP}$	–	V	CMOS Mode
Input high voltage on P0.0 & P0.1	V_{IHP0}	SR	$0.7 \times V_{DDP}$	V_{DDP}	V	CMOS Mode
Input high voltage on RESET pin	V_{IHR}	SR	$0.7 \times V_{DDP}$	–	V	CMOS Mode
Input high voltage on TMS pin	V_{IHT}	SR	$0.75 \times V_{DDP}$	–	V	CMOS Mode
Input Hysteresis	HYS	CC	$0.03 \times V_{DDP}$	–	V	CMOS Mode ¹⁾
Input Hysteresis on XTAL1	$HYSX$	CC	$0.07 \times V_{DDC}$	–	V	¹⁾
Input low voltage at XTAL1	V_{ILX}	SR	$V_{SS} - 0.5$	$0.3 \times V_{DDC}$	V	

Electrical Parameters

4.2.3 ADC Characteristics

The values in the table below are given for an analog power supply between 4.5 V to 5.5 V. The ADC can be used with an analog power supply down to 3 V. But in this case, the analog parameters may show a reduced performance. All ground pins (V_{SS}) must be externally connected to one single star point in the system. The voltage difference between the ground pins must not exceed 200mV.

Table 40 ADC Characteristics (Operating Conditions apply; $V_{DDP} = 5V$ Range)

Parameter	Symbol		Limit Values			Unit	Test Conditions/ Remarks
			min.	typ .	max.		
Analog reference voltage	V_{AREF}	SR	$V_{AGND} + 1$	V_{DDP}	$V_{DDP} + 0.05$	V	¹⁾
Analog reference ground	V_{AGND}	SR	$V_{SS} - 0.05$	V_{SS}	$V_{AREF} - 1$	V	¹⁾
Analog input voltage range	V_{AIN}	SR	V_{AGND}	–	V_{AREF}	V	
ADC clocks	f_{ADC}		–	24	25.8	MHz	module clock ¹⁾
	f_{ADCI}		–	–	10	MHz	internal analog clock ¹⁾ See Figure 35
Sample time	t_S	CC	$(2 + INPCR0.STC) \times t_{ADCI}$			μs	¹⁾
Conversion time	t_C	CC	See Section 4.2.3.1			μs	¹⁾
Total unadjusted error	TUE	CC	–	–	1	LSB	8-bit conversion ²⁾
			–	–	2	LSB	10-bit conversion ²⁾
Differential Nonlinearity	$ EA_{DNL} $	CC	–	1	–	LSB	10-bit conversion ¹⁾
Integral Nonlinearity	$ EA_{INL} $	CC	–	1	–	LSB	10-bit conversion ¹⁾
Offset	$ EA_{OFF} $	CC	–	1	–	LSB	10-bit conversion ¹⁾
Gain	$ EA_{GAIN} $	CC	–	1	–	LSB	10-bit conversion ¹⁾
Overload current coupling factor for analog inputs	K_{OVA}	CC	–	–	1.0×10^{-4}	–	$I_{OV} > 0^{1)3)}$
			–	–	1.5×10^{-3}	–	$I_{OV} < 0^{1)3)}$